Company Profile

BIWIN STORAGE TECHNOLOGY CO., LTD.

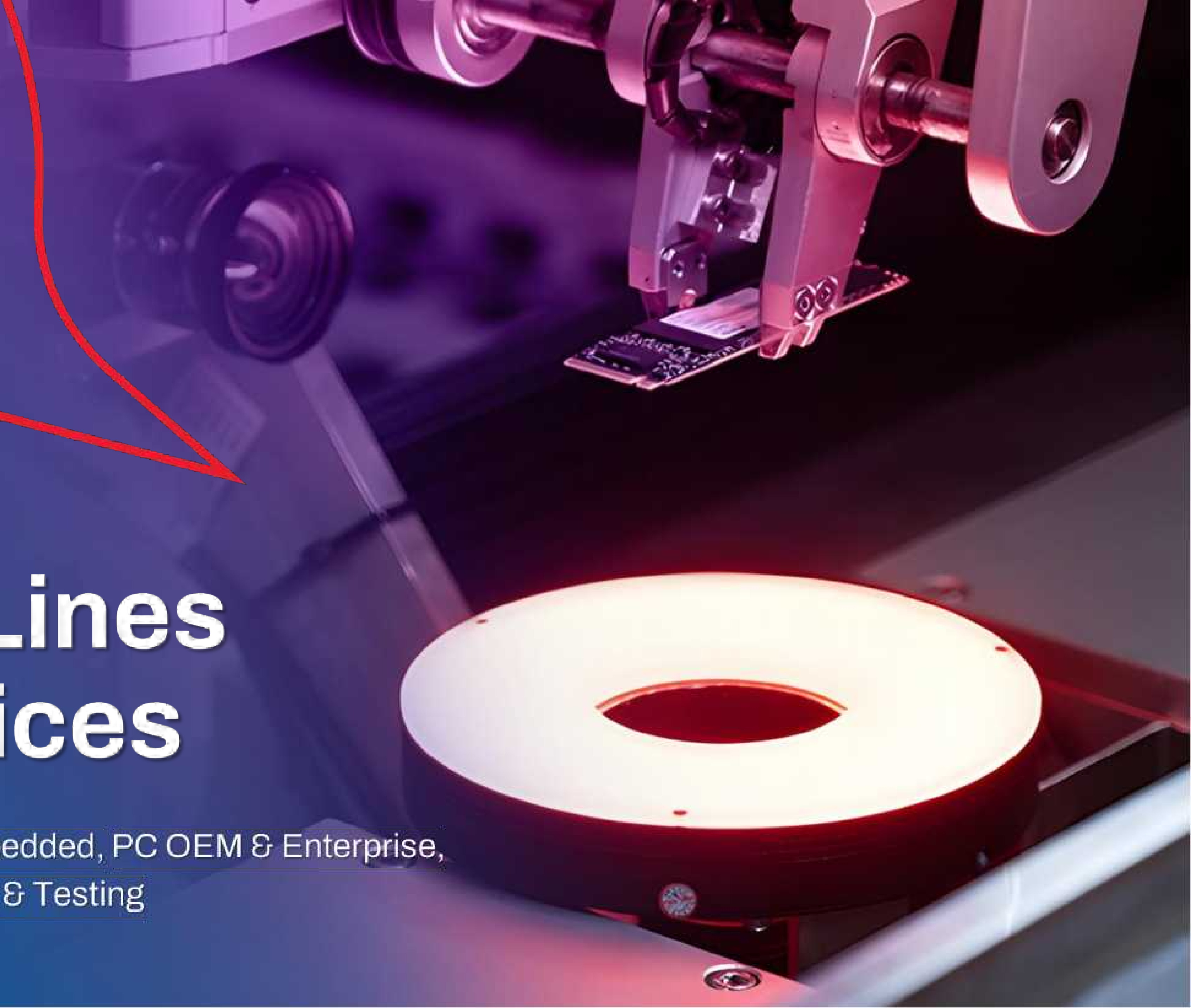
2025 Q1

BIWIN Storage Technology CO., Ltd. (SSE STAR Market, Stock Symbol: 688525) produces high quality NAND flash storage and is now known in embedded, consumer, corporate and industrial segments for its independent development capabilities in **hardware, software, firmware and storage algorithms.**

Our founders started in the flash storage business in 1995, in Shenzhen, China, embracing the **"WIN-WIN" business philosophy** that would later become the hallmark for BIWIN.

In 2009, they made **a key decision for the business: to add IC encapsulation (or IC packaging) process into the factory** A remarkable milestone that the vast of majority of competing companies still don't have (they outsource the process or buy the packaged IC). This successful step led to the 2010 creation of the company we know today.

CONTENTS



01

Product Lines and Services

Industrial & Automotive, Embedded, PC OEM & Enterprise, Consumer, and IC Packaging & Testing

Product Lines, Storage & Memory Solutions

Industrial & Automotive

Industrial:
- SATA SSD (2.5”, mSATA, M.2 2280/2242)
- PCIe SSD (M.2 2280/2242)
- SODIMM/UDIMM (DDR4, DDR5)
- ECC SODIMM/UDIMM (DDR4)
- SD/microSD Card
- eMMC
- SPI NOR

Automotive:
- eMMC (5.1)
- UFS (3.1)
- SPI NOR

… and more

Embedded

- eMMC (5.1, 5.2)
- UFS (2.1, 2.2, 3.1)
- ePOP
- eMCP
- uMCP
- LPDDR (3, 4/4X, 5/5X)
- BGA SSD (PCIe 3.0/4.0)

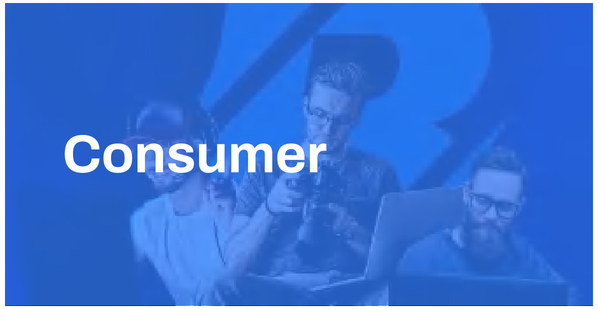
… and more

PC OEM & Enterprise

PC OEM:
- SATA SSD (2.5”)
- M.2 SSD (M.2 2280/2242/2230)
- SODIMM (DDR4, DDR5)
- UDIMM (DDR4, DDR5)

Enterprise:
- 2.5-inch SATA SSD (U.2)
- PCIe SSD (U.2, E1.S, E3.S)
- RDIMM (DDR5)
- CXL DRAM (AIC, E3.S)

… and more



Consumer

- SATA SSD (2.5”)
- PCIe SSD (M.2 2280/2230)
- SODIMM/UDIMM (DDR4, DDR5)
- CUDIMM (DDR5)
- Portable SSD
- CFexpress Type-A Card
- CFexpress Type-B Card
- SD/microSD Card
- USB Flash drive
- Card Reader

… and more

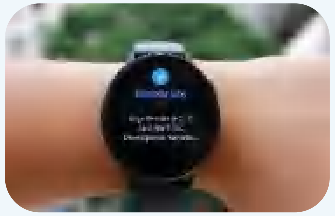
Products and Applications

Mobile Smart Devices

eMMC/UFS

LPDDR4X/5X

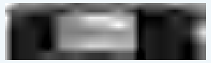
ePOP



PC

DDR4/DDR5

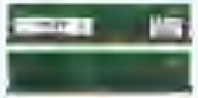
eSSD



M.2 SSD

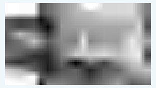
Data Center

2.5-inch SSD

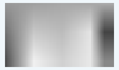


RDIMM

Industry Terminals



SATA DOM



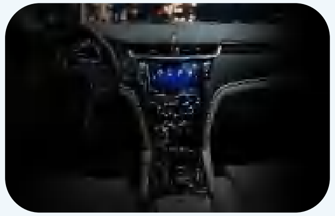
mSATA

Smart Automotive

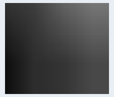
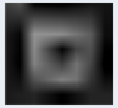
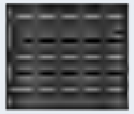
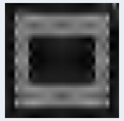
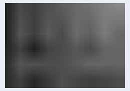
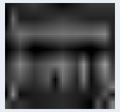
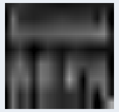
eMMC/UFS

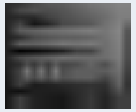
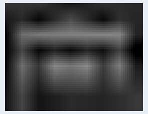
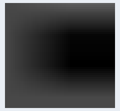
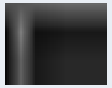
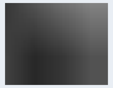
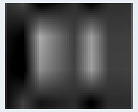
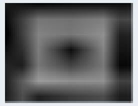
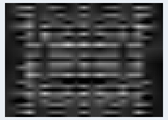
LPDDR4X/5X

BGA SSD

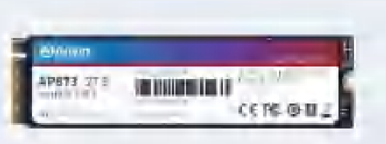
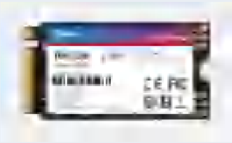
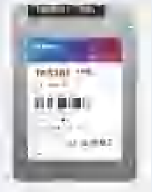


Embedded Chips

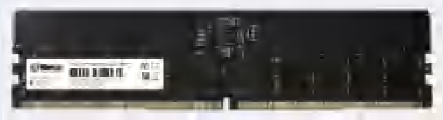
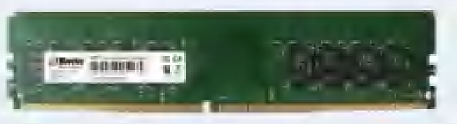
Product	**eMMC**		**LPDDR**				**uMCP**	
Type	**eMMC 5.1**	**eMMC 5.1**	**LPDDR4X**	**LPDDR5/5X**	**LPDDR5/5X**	**LPDDR5/5X**	**UFS 2.2 + LPDDR4X**	**UFS 2.2 + LPDDR5**
Photo								
Dimensions (mm)	8.0 x 7.5 x 0.75	11.5 x 13.0 x 0.9	10.0 x 14.5 x 1.0 10.0 x 15.0 x 1.0	12.4 x 15.0 x 1.0	14.0 x 12.4 x 0.8	8.2 x 12.4 x 0.8	11.5 x 13.0 x 1.2	11.5 x 13.0 x 1.2
Packaging	FBGA 153b	FBGA 153b	FBGA 200b	FBGA 315b	FBGA 496b	FBGA 245b	FBGA 254b	FBGA 297b
Max.Capacity	64GB	512GB	64Gb	64Gb	128Gb	64Gb	512GB+64Gb	256GB+64Gb

Product	**eMCP**		**ePOP**			**UFS**	**BGA SSD**	
Type	**eMMC 5.1 + LPDDR3**	**eMMC 5.1 + LPDDR4X**	**eMMC 5.1 + LPDDR3**	**eMMC 5.1 + LPDDR4X**	**eMMC 5.1 + LPDDR5X**	**UFS2.2/3.1**	**PCIe GEN 4X2**	**PCIe GEN 4X4**
Photo								
Dimensions (mm)	11.5 x 13 x 1.0	11.5 x 13 x 1.0	10.0 x 10.0 x 0.9	8.0 x 9.5 x 0.8 8.6 x 10.4 x 0.65	8.0 x 9.5 x 0.7	11.5 x 13.0 x 1.2	11.5 x 13.0 x 1.2	16.0 x 20.0 x 1.4
Packaging	FBGA 221b	FBGA 254 Ball	ePOP 136b	ePOP 144b	ePOP 201b	FBGA 153b	FBGA 345b	FBGA 291b
Max.Capacity	16GB+16Gb	128GB+64Gb	32GB+8Gb	64GB+32Gb	64GB+32Gb	512GB	512GB	1TB

SSDs and Memory Cards

Form Factors	**NVMe M.2 2280**	**NVMe M.2 2242**	**NVMe M.2 2230**	**2.5 inch**
Photos				
Capacity	512 GB - 2 TB	32 GB - 2 TB	256 / 512 GB	128 GB - 2 TB
Form Factors	SATA M.2 2280	SATA M.2 2242	mSATA	2.5 U.2
Photos				
Capacity	32 GB - 2 TB	32 GB - 2 TB	32 GB - 2 TB	32 GB - 2 TB
Form Factors	E3.S	U.2	E1.S	SD Card / microSD Card
Photos				
Capacity	15.36 TB	3.84 TB	12.8 TB	32 - 256 GB

DRAM Modules

DDR	**DDR5**	**DDR5**	**DDR5**	**DDR5**
DIMM	SODIMM	UDIMM	CU-DIMM	LPDDR5 CAMM2
Photos				
Capacity	16 GB / 32 GB	16 GB / 32 GB	16 GB / 32 GB	16 GB / 32 GB / 64 GB
Data Rate (up to)	4800 MT/s / 5600 MT/s	4800 MT/s / 5600 MT/s	6400 MT/s ~ 8800 MT/s	6400 MT/s ~ 9600 MT/s
Model	**DDR4**	**DDR4**	**DDR4**	**DDR4**
DIMM	ECC SODIMM Wide-Temperature	ECC UDIMM Wide-Temperature	Non-ECC SODIMM	Non-ECC UDIMM
Photos				
Capacity	8 GB / 16 GB	8 GB / 16 GB	4 GB / 8 GB / 16 GB	8 GB / 16 GB
Data Rate (up to)	3200 Mbps	3200 Mbps	3200 Mbps	3200 Mbps

Official Licensed Consumer Brands

Brand License

BIWIN is the HP business partner and official licensee, with HP for the marketing, sale, promotion, and distribution of aftermarket internal solid state drives, external portable SSDs, synchronous dynamic random access memory (SDRAM) and memory cards for the consumer market.

Global Exclusive License

In July 2020, BIWIN and Acer reached a global exclusive brand licensing agreement. We have become the exclusive global brand licensee of Acer and Predator: memory, SSD, eSports memory, portable SSD, and other products.

Global Exclusive License

Predator branded storage products are designed and manufactured by BIWIN Storage Technology Company, a leading maker of high-end gaming memory modules and SSDs for eSports and gaming enthusiasts.

Brand License

Lenovo's story has always been about shaping computing intelligence to create a better world. By designing, producing, and marketing an officially licensed range of Lenovo branded SSDs, BIWIN embraces Lenovo's vision of Smarter Technology for All.

Biwin Consumer Brand

It's a digital world. We all need our digital devices-- and these devices need the best storage and memory to perform at their best.

For decades, Biwin has made the critical storage and memory in many of the leading digital devices that have defined our digital world.

Our consumer brand brings you the best of our experience, **a range of SSDs, DRAM, memory cards and related accessories** that will help you get the most out of your devices.

Our cutting-edge facilities use the latest technologies including our own chip packaging, software and hardware labs, state-of-the-art clean rooms, and our own award-winning manufacturing equipment. We are especially proud of our extraordinary rigorous chain of testing that assures you we're working to bring you the best in reliability.

Whether at work, at play or entertainment, we believe you can count on winning with our Biwin brand.

Biwin, Built to Win.

BLACK OPAL (Gaming)

Biwin Black Opal is designed for gamers, enthusiasts, modders and overclockers seeking top-tier performance.The result of years of experience in SSDs and DRAM manufacturing, Black Opal durability matches the more strenuous needs of gamers, content providers and professional users.

OC
OPTIMIZED
Splitsecond

What is OC Lab?

OC Lab is an overclocking laboratory focused on maximizing memory module performance, pushing the limits of memory overclocking. Using advanced chip selection, OC Lab rigorously chooses top-quality memory chips and fine-tunes them to unlock exceptional overclocking potential, thereby delivering unmatched speed, stability, and reliability.

Amber (Mobility)

Biwin Amber is ideal for professionals on the go requiring superior mobile storage solutions.

Biwin (Mainstream)

The Biwin consumer brand offers the best of Biwin's experience, a range of SSDs, DRAM, memory cards and related accessories that will help you get the most out of your devices.

Supply Chain & Business Partners*

Mobile & Wearable Smart Devices	Google Meta ZTE中兴 FOXCONN SKYWORTH 创维 TCL TRANSSION 传音控股 WINGTECH 闻泰科技 WATER WORLD TINNO 天珑 大联科技 HQ CNCE TINNO 天珑移动 WEIBU 微步 [illegible] oppo [illegible] ring Centerm
Enterprise Storage	[illegible] 清华同方 inspur 浪潮
PC	acer Lenovo hp
Industrial Storage	mindray Streamax 锐明 STAR-NET 星网锐捷

* Each trademark belongs to its respective owner.

*** BIWIN Embedded Storage Shipments, No. 8 Worldwide (Source: China Flash Market)**

Supply Chain & Business Partners*

Wafer Manufacturers

SAMSUNG
Micron
KIOXIA
NANYA
Western Digital
CXMT

Controller Manufacturers

Biwin Storage Technology
MaXio
INNOGRIT 英韧科技
SiliconMotion

R&D

Biwin Storage Technology

- Medium Research & Screening
- Firmware Algorithms Development
- Software & Hardware Design
- Packaging Design Simulation
- Testing & Development

Packaging & Testing

Biwin Storage Technology

- Memory Chip Packaging & Testing
- Module Manufacturing & Testing
- Advanced Packaging & Testing
- Testing Equipment Development

Verification

Qualcomm
MEDIATEK
Microsoft
AMD
intel
君正 Ingenic
Acronis

Products / Brands

Product Types

- eMMC Embedded
- SSD SSD
- DRAM Module
- Memory Card

Brands

Biwin Storage Technology
Biwin
acer
PREDATOR
Lenovo

* Each trademark belongs to its respective owner.

02

R&D Capabilities

Storage Medium Characteristic Analysis, Firmware Development, and Automated Testing

Increasing Investment in R&D for New Productivity

01. Development in Solutions

Building Product Competitiveness

- Increasing investment in **media characteristics research, firmware, software & hardware, and testing development.**
- Improving product competitiveness by optimizing **performance, power consumption, capacity, size, etc.**
- Developing innovative products in **smart wearables, industrial and automobile solutions, high-performance mobile phones/PCs, CXL, and more.**

02. IC Design

Self-developed controller

- BIWIN has produced the tape-out and verification of our **first Storage Controller**—demonstrating excellent performance.
- BIWIN develops the next generation **12nm/6nm** advanced storage controller to meet the needs of AI applications

03. Intellectual Property Rights

Increasing Investment in Core R&D

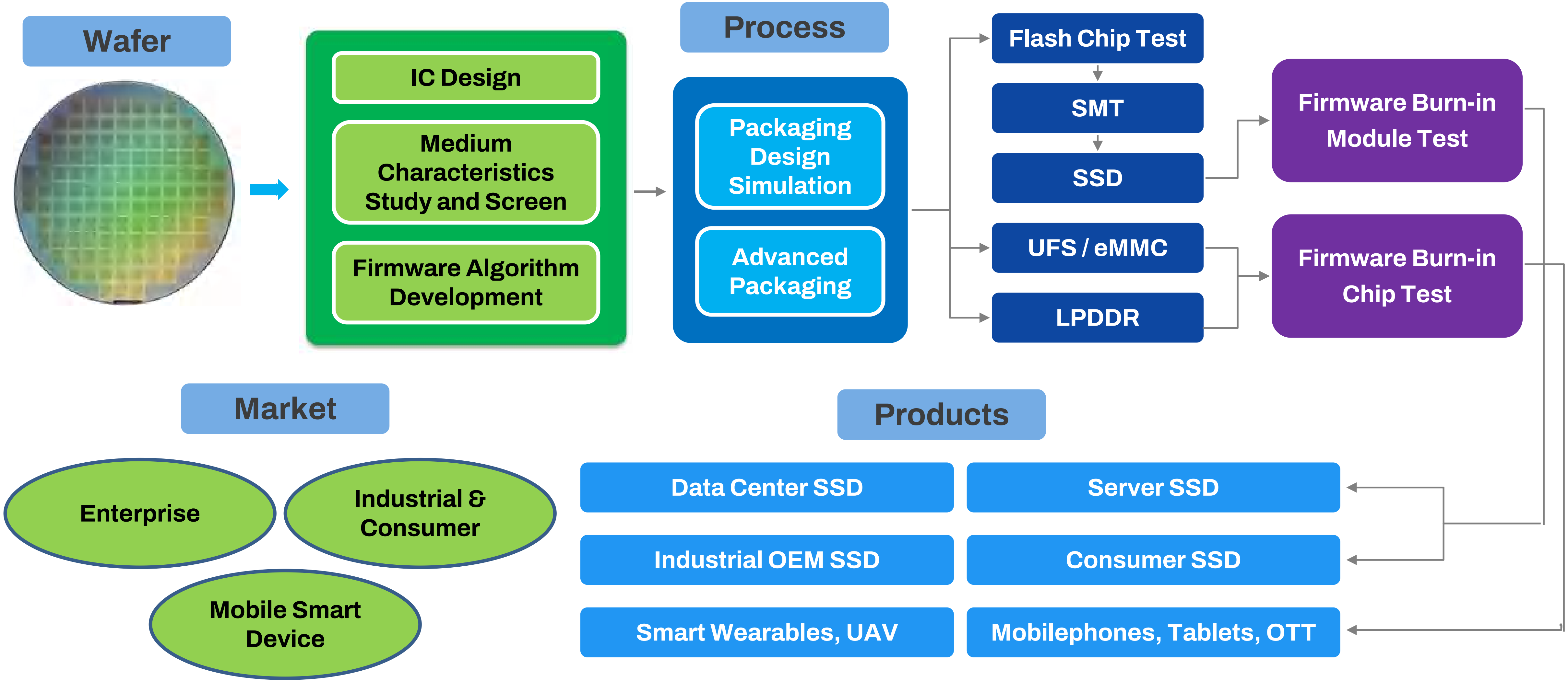
- The proportion of R&D investment in total revenue is approximately **7%.**
- BIWIN has obtained a total of **307** domestic and overseas patents and **27** software copyrights.
- In 2023, 84 new patent applications were filed, with 56 patents granted, and 1 new IC layout design patent was granted.

04. Test equipment

Software + Hardware + Platform

- BIWIN develops storage testing machines, ranging from **ATE, BI to SLT**, among which the TY-S101A testing machine won the "**Most Innovative Award**".

From R&D to Packaging & Testing: Integration Services



Wafer

- IC Design
- Medium Characteristics Study and Screen
- Firmware Algorithm Development

Process

- Packaging Design Simulation
- Advanced Packaging

- Flash Chip Test
- SMT
- SSD
- UFS / eMMC
- LPDDR

- Firmware Burn-in Module Test
- Firmware Burn-in Chip Test

Market

- Enterprise
- Industrial & Consumer
- Mobile Smart Device

Products

- Data Center SSD
- Server SSD
- Industrial OEM SSD
- Consumer SSD
- Smart Wearables, UAV
- Mobilephones, Tablets, OTT

From R&D to Packaging & Testing: Integration Services

Design & Manufacturing Integration VS **BIWIN's Wafer-to-Packaging-to-Delivery Integration**

IC Design

Wafer Manufacturing

Wafer Features Study + Controller Design & Firmware Development + Hardware Development

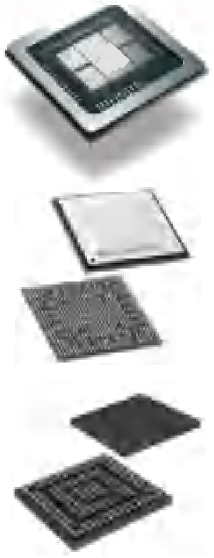
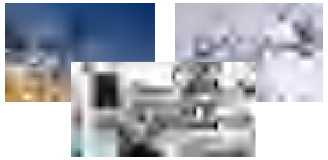
Chip Packaging

Chip Testing

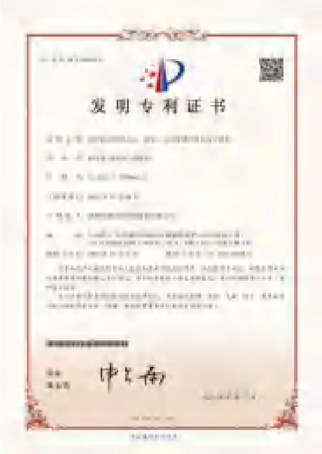
Platform Adaptation and Verification

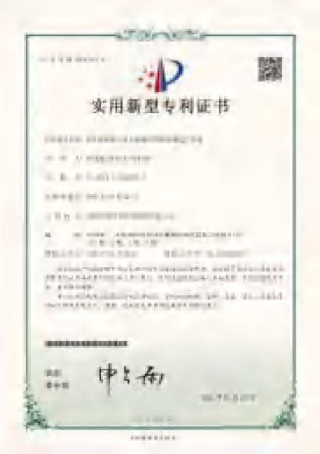
Delivery

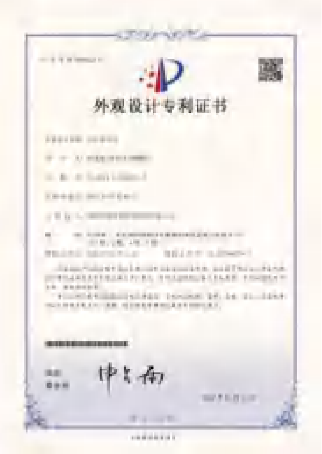
A One-stop Service to Bring Your Products to Market Faster

Wafer	Design	Production	Product
SAMSUNG tsmc CanSemi micron UMC 	• Packaging Solutions • Testing Solutions • Module Solutions • Reliability Validation • Simulation & Eye Diagrams • Substrates • Frames • Masks • Stencils • Etc.	**Packaging:** • SiP • FC CSP/BGA • WB BGA/QFN • Module • Bumping • Fanin/Fanout • 2.5D/3D • Chiplet  **Testing:** • CP (Wafer Probing) • FT • ATE • Burn-in (Aging Test) • SLT (System-Level Testing) 	 **Consumer-Grade**  **Automotive**  **Industrial-Grade**

Our Innovation Adds Growth in Intellectual Property


发明专利证书


实用新型专利证书


外观设计专利证书


The United States of America

The Director of the United States Patent and Trademark Office

United States Patent


United States of America

United States Patent and Trademark Office

BIWIN


中华人民共和国国家版权局

计算机软件著作权登记证书

Types		Patented	Patent-pending	Total
Patents (307)	Invention Patents	95	181	276
	Utility Model Patents	148	51	199
	Appearance Patents	64	7	71
Computer Software Copyrights (27)		27	9	36
Others (157)	International Trademarks	35	2	37
	Chinese Trademarks	121	24	145
	IC Layout Design	1	0	1
Total		**491**	274	765

03

Manufacturing Capabilities

Monthly Productivity, Automated Testing System,
Quality Control, and Advanced IC Packaging & Testing

GBAT (Greater Bay Advanced Technology Co., Ltd.)

Greater Bay Advanced Technology Co., Ltd. (GBAT), founded in December 2016, is a wholly-owned subsidiary of Shenzhen BIWIN Storage Technology Co., Ltd. (Stock Code: 688525).

With over 1,500 employees, GBAT covers 38,000 square meters of land and has a total building area of 110,000 square meters.

GBAT specializes in advanced memory packaging and testing, and storage-computer integration. It masters cutting-edge manufacturing capabilities, including **FC-BGA (Flip-Chip Ball Grid Array)/FC-CSP (Flip-Chip Chip Size Package), 16-layer stacked die, ultra-thin die (30-40 μm), FOD (Foreign Object Debris) management, vertical wire bonding, and multi-chip heterogeneous integration (SiP)**, all of which meet world-class industry standards.

With a core team of over 200 senior engineers and talent from both local and international backgrounds, GBAT’s products are widely applied in sectors such as mobile smart terminals, personal computers, industrial terminals, data centers, intelligent vehicles, and portable storage.

GBAT is committed to becoming a distinguished benchmark for advanced testing and packaging solutions in the Greater Bay Area, focusing on "advanced storage + logic chips + automotive-grade" packaging and testing capabilities.

Monthly Productivity (Wire Bonding & Flip Chip)

Year		BGA/LGA Substrate Product Line (12-inch wafer)	Flip Chip FCCSP & FCBGA		Module Product Line	
			FC Line	Monthly	SSD	Memory
2023	A1: Full Capacity	30,000 units/month	1	5 million	1.5 million/month	100K/month
2024	A2: Approaching	60,000 units/month	3	15 million	2 million/month	200K/month
2025	A3: Approaching	100,000 units/month	6	30 million	3 million/month	300K/month

Each "A" building has 6 floors, with 3,300 square meters per floor.

A1 Building: FC 2 lines | DB 100 units

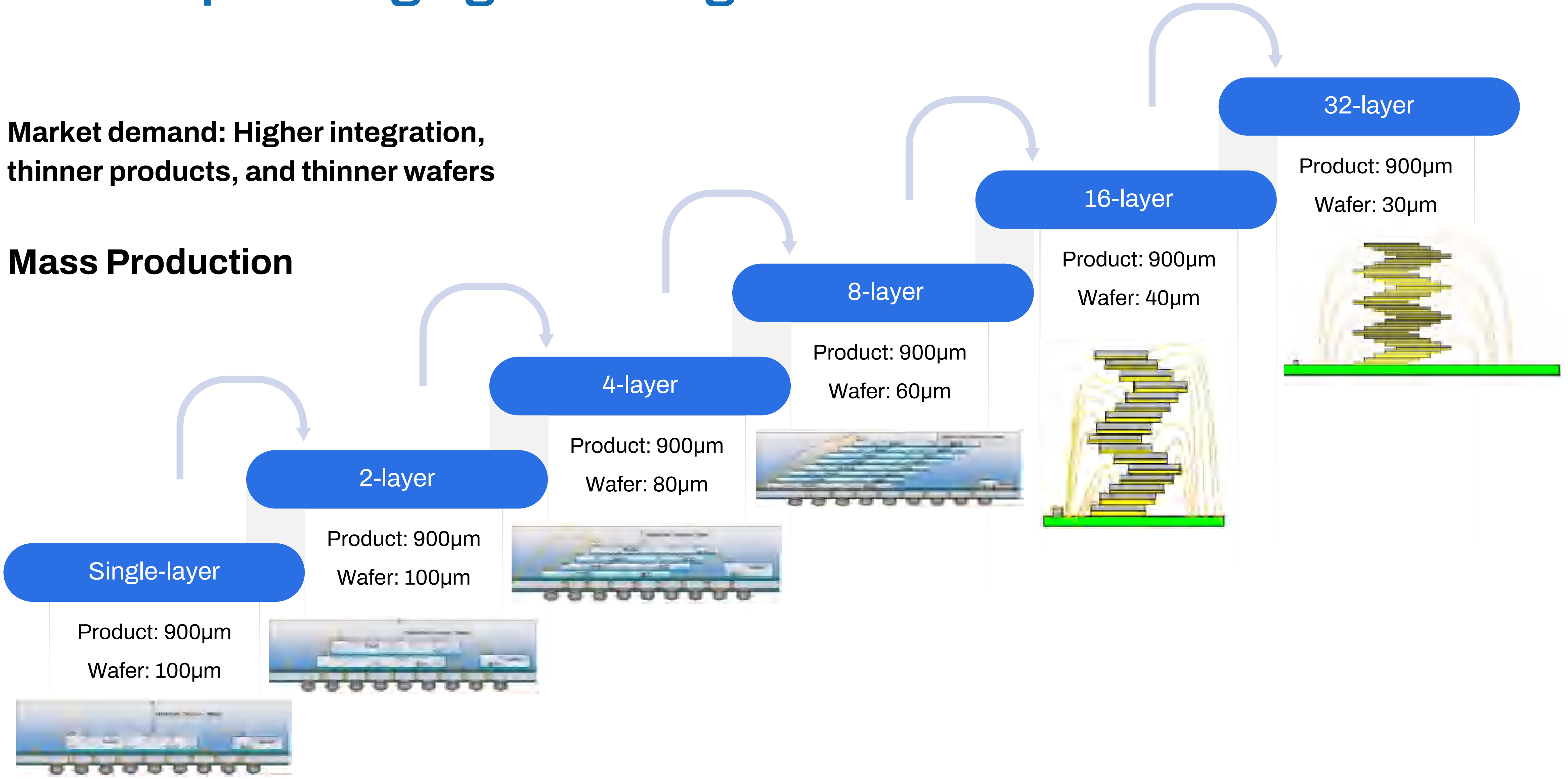
A2 Building: FC 2 lines | DB 100 units

A3 Building: FC 2 lines | DB 150 units

BIWIN Chip Packaging Advantages

Market demand: Higher integration, thinner products, and thinner wafers

Mass Production



Single-layer

Product: 900µm

Wafer: 100µm

2-layer

Product: 900µm

Wafer: 100µm

4-layer

Product: 900µm

Wafer: 80µm

8-layer

Product: 900µm

Wafer: 60µm

16-layer

Product: 900µm

Wafer: 40µm

32-layer

Product: 900µm

Wafer: 30µm

Automated Testing Systems

Our Great Team

Our core members come from first-tier wafer OEMs and bring rich experiences in testing and R&D.

Testing Tools

We own optimized test algorithms and automation tools. Our use case coverage and automation level are at the forefront of the industry.

DVT

We boast a meticulous design verification test (DVT) to ensure product quality from front-end R&D.

PVT

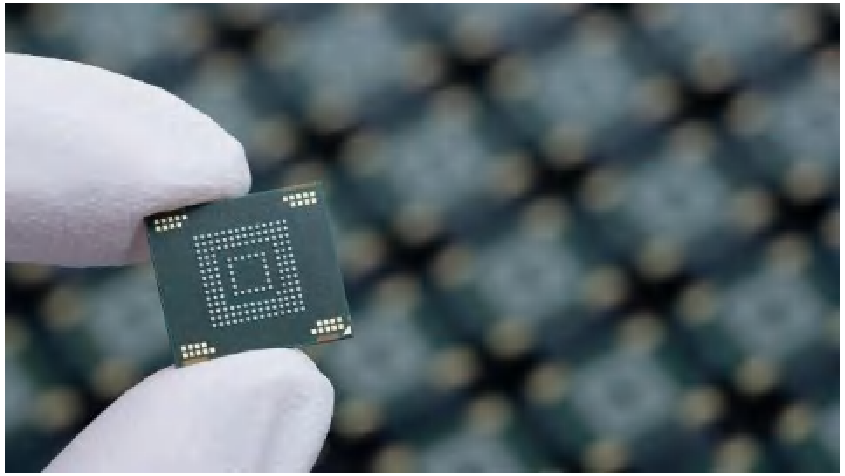
We own a product verification test (PVT) to ensure exceptional performance and stable quality of our products.

Electrical Tests	SI Tests	Application Tests	Compatibility Tests	Verification Tests
• O/S • Functional • Power Consumption AC Parameters • DC Parameters	• Signal Integrity • SATA Eye Pattern	• Basic Functions • Performance • WA	• ATACT Command • NCQ / Trim • Diverse Platforms & OS Compatibility Tests	• RDT • EST • MST • Power Cycle • Dormancy • Reboot

Patented Test Equipment Invented by BIWIN

Testing Capabilities & Services

- We offer a strong team with rich experience in IC testing.
- We are experienced in testing SSD, DDR, SoC and other chips– with the experience of success stories from well-known companies.
- With a complete delivery system and solutions, self-developed test equipment from BI to SLT, BIWIN delivers fast, efficient, and seamless customer support to help companies become leaders in their industries for the product quality, productivity, and cost.



Customized Turnkey Solution 1

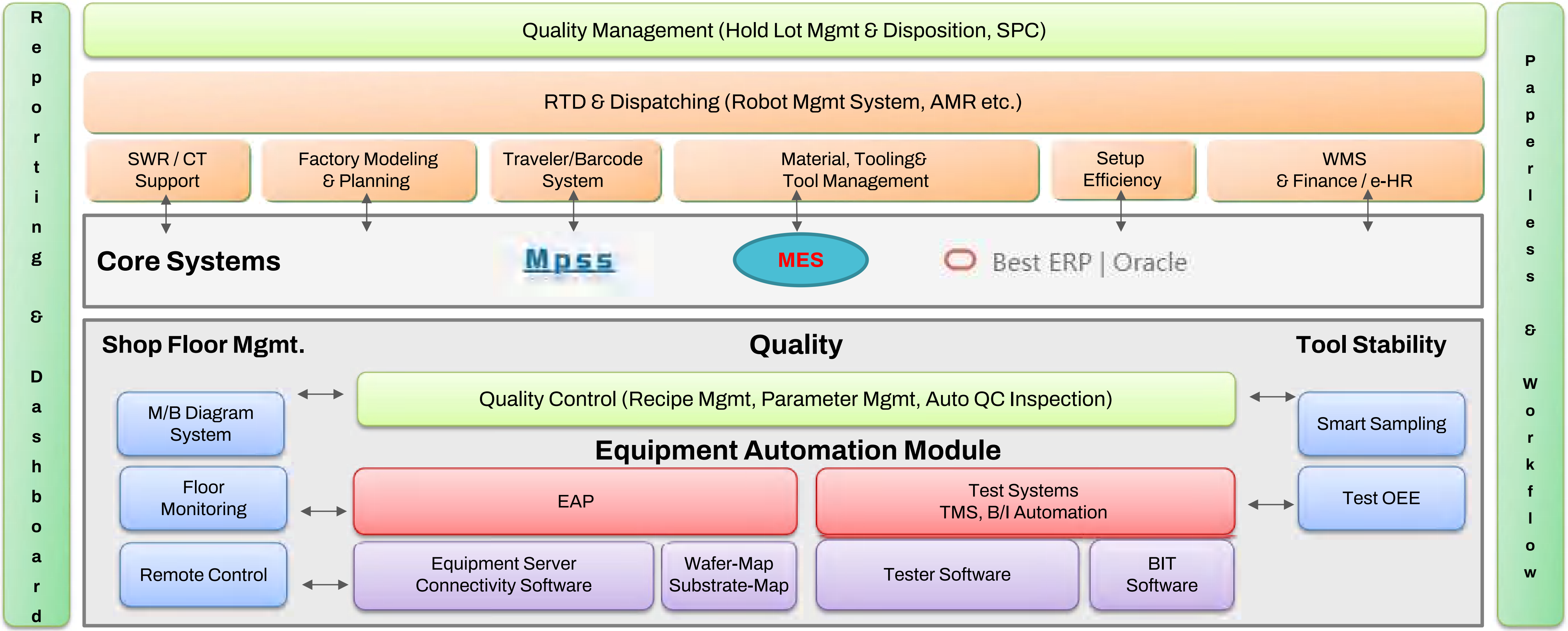
- BIWIN offers customized service for test cases, software and reliability tests.
- Our experienced R&D team analyses the demand and any pain points to provide our customers expert turnkey solutions for project delivery (from design to implementation).

Testing Service 2

- BIWIN provides testing services for products including ICs and modules. Our experience plus quality testing resources and professional testing equipment ensure product quality, productivity, and delivery.

Quality Control Capabilities

Advanced IT Automation System I Robotic Automatic Loading/Unloading



Reporting & Dashboard

Quality Management (Hold Lot Mgmt & Disposition, SPC)

RTD & Dispatching (Robot Mgmt System, AMR etc.)

SWR / CT Support

Factory Modeling & Planning

Traveler/Barcode System

Material, Tooling& Tool Management

Setup Efficiency

WMS & Finance / e-HR

Core Systems

Mpss

MES

Best ERP | Oracle

Shop Floor Mgmt.

Quality

Tool Stability

M/B Diagram System

Floor Monitoring

Remote Control

Quality Control (Recipe Mgmt, Parameter Mgmt, Auto QC Inspection)

Equipment Automation Module

EAP

Test Systems TMS, B/I Automation

Equipment Server Connectivity Software

Wafer-Map Substrate-Map

Tester Software

BIT Software

Smart Sampling

Test OEE

Paperless & Workflow

Quality Management System


BIWIN STORAGE TECHNOLOGY CO., LTD.

ISO 9001:2015

ISO9001:2015


Certificate of Registration

IATF:16949


sira CERTIFICATION

环境管理体系认证证书

ISO14001:2015


信息安全管理体系认证证书

ISO27001


IECQ Certificate of Conformity

Hazardous Substance Process Management

IECQ-QC 080000


社会责任管理体系

认证证书

惠州佰维存储科技有限公司

SA8000:2014

SA8000:2014

Certifications Obtained by BIWIN:

ISO9001 / IATF16949 / ISO14001 / ISO27001 / QC080000 / SA8000

GBCC (Greater Bay Chiplet Company Co., Ltd.)

Greater Bay Chiplet Company Co., Ltd. (GBCC), established in September 2023, is a wholly-owned subsidiary of Shenzhen BIWIN Storage Technology Co., Ltd. (Stock Code: 688525).

GBCC operates on a 10,000-square-meter site and will feature a state-of-the-art cleanroom facility covering 70,000 square meters.

GBCC specializes in **advanced wafer-level packaging for memory chips and the integration of memory and computer chips, mastering cutting-edge wafer bumping, fan-in, and 2.5D packaging technologies**. With a core team of top-tier talents from both local and international backgrounds, GBCC provides comprehensive services in memory and logic chip integration, along with testing and R&D capabilities.

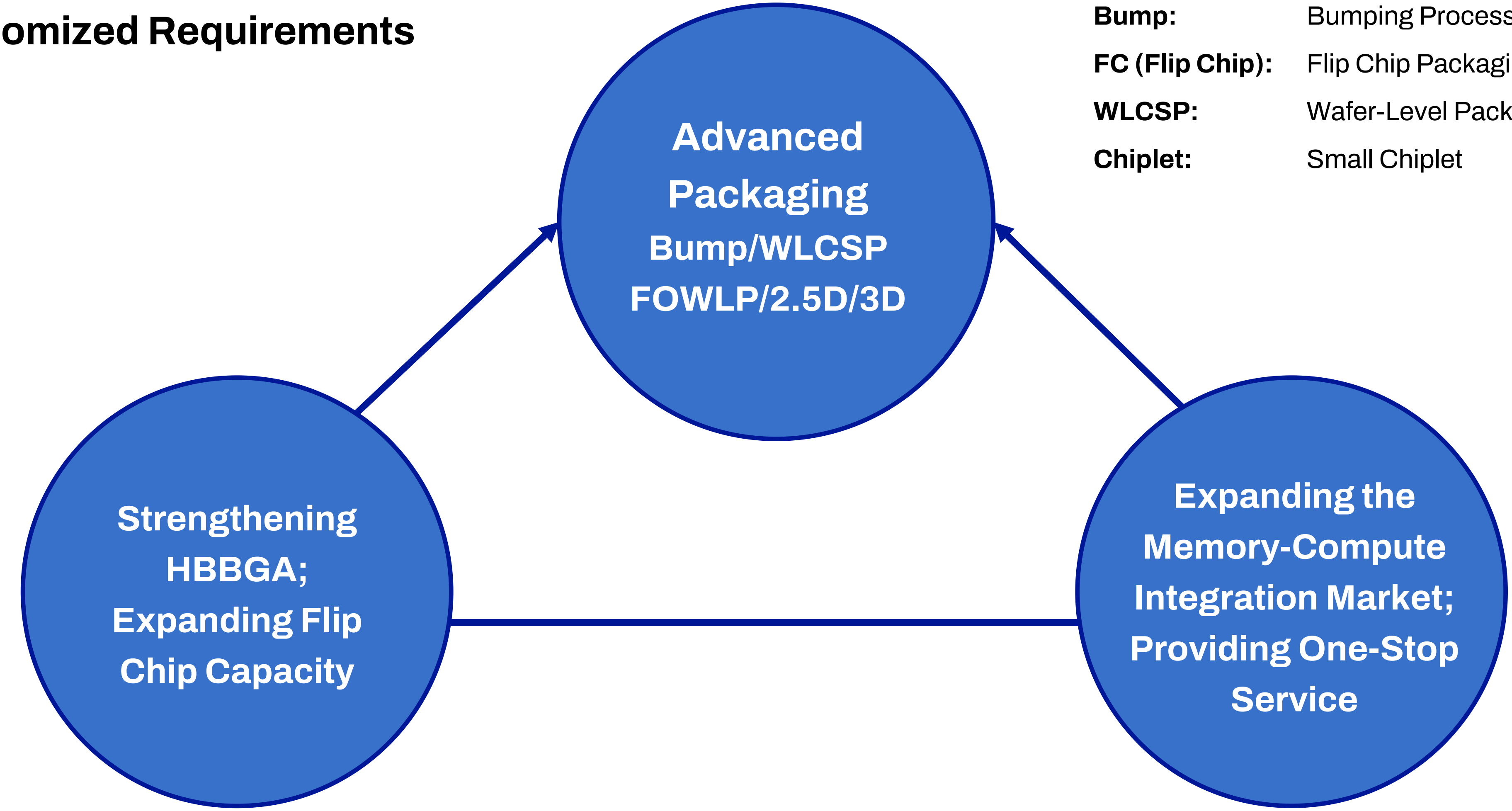
The company has established a comprehensive, internationally skilled team specializing in wafer-level memory-computer chip packaging services. Its products are widely applied in mobile smart terminals, edge computing, data centers, intelligent vehicles, and other fields of information technology.

GBCC is committed to becoming a leading benchmark for advanced wafer-level packaging and testing solutions in the Greater Bay Area, with the capability to integrate 'advanced memory + computer chips'.

Development Strategy

Meeting Customers' Evolving Needs and Customized Requirements

HBBGA:	Hybrid System-Level BGA Packaging
Bump:	Bumping Process
FC (Flip Chip):	Flip Chip Packaging
WLCSP:	Wafer-Level Packaging
Chiplet:	Small Chiplet

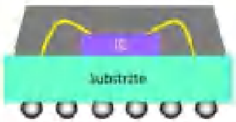
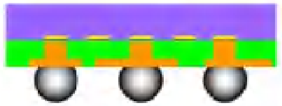
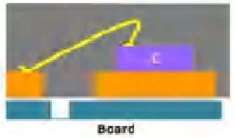
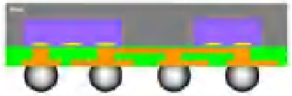
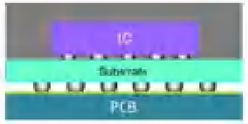
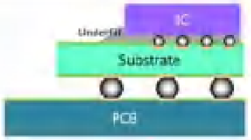


Advanced Packaging
Bump/WLCSP
FOWLP/2.5D/3D

Strengthening HBBGA; Expanding Flip Chip Capacity

Expanding the Memory-Compute Integration Market; Providing One-Stop Service

Advanced Packaging Capabilities

Existing Plant Capacities			Planned Capacities		
Hybrid BGA (SiP)		- Size: 3x3 ~ 30x30 mm - SiP (FC + WB) - Chip Thickness: 40 μm, 16-layer stacked Die	**Bump (Cu Pillar)**		- L/S: 2 ~ 10 μm - Height: 18 ~ 150 μm - Bump Size: 30 μm
WB BGA/LGA		- Size: 2x2 ~ 30x30 mm - Chip Thickness: 40 μm - 16-layer Die stacking	**Fanin (WCSP)**		- L/S: 2 ~ 10 μm - 2 ~ 6 Layers - LTPI@>80% Cu Density
WB QFN		- Framework: 100 x 300 - Wettable Flank - Plasma Saw	**Fanout (EMC)**		- L/S: 2 ~ 10 μm - Single Chip & Multi Chips - Face Down/Up & RDL Frost
Module		- PCIe, SATA, M.2 - DRAM Module - Auto SSD	**TSV**		- Diameter: 2 ~ 100 μm - Thickness: 10 ~ 200 μm
FlipChip (CSP)		- Size: 15 x 15 mm - Bump Size: 40 μm - I/O: ~ 450	**HBM**		- Chip to Chip (D2D) - 4 ~ 12 layers stacking - Double Bump Flip-chip, 30 μm & TCB
FlipChip (BGA)		- Size: 50 x 50 mm - Bump Size: 40 μm - I/O: ~ 2000	**Chiplet**		- Bumping / Micro Bump / RDL - WLCSP (Fanin/Fanout) - TSV & Hybrid Bonding

Showcase: SiP MP Product

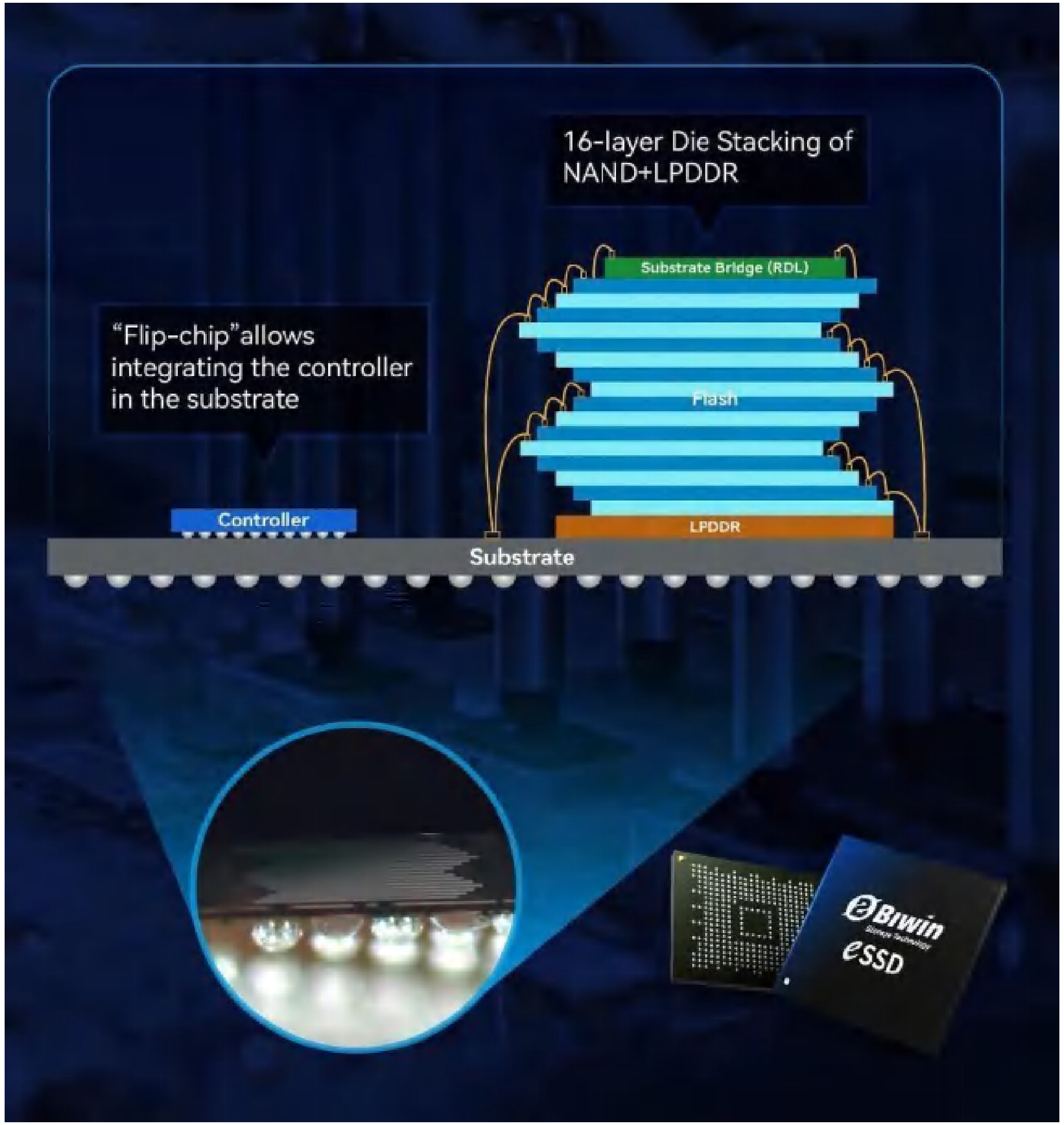
Advantages:

- Smaller size, 0.7 mm
- 7*7 ~31*31
- Warpage control (thickness < 40μm in high temperature)

Key Techniques:

- 40 μm Die (LG + SDBG)
- Die-stacking, narrow-pitch wire bonding, FOW, FMS, C-Molding
- Underfill
- Nitto / Disco / Fasford / KNS / BESI / TOWA

System in Package (SiP) is a method used for bundling multiple integrated circuits (ICs) and passive components into a single package where all work together.


16-layer Die Stacking of NAND+LPDDR

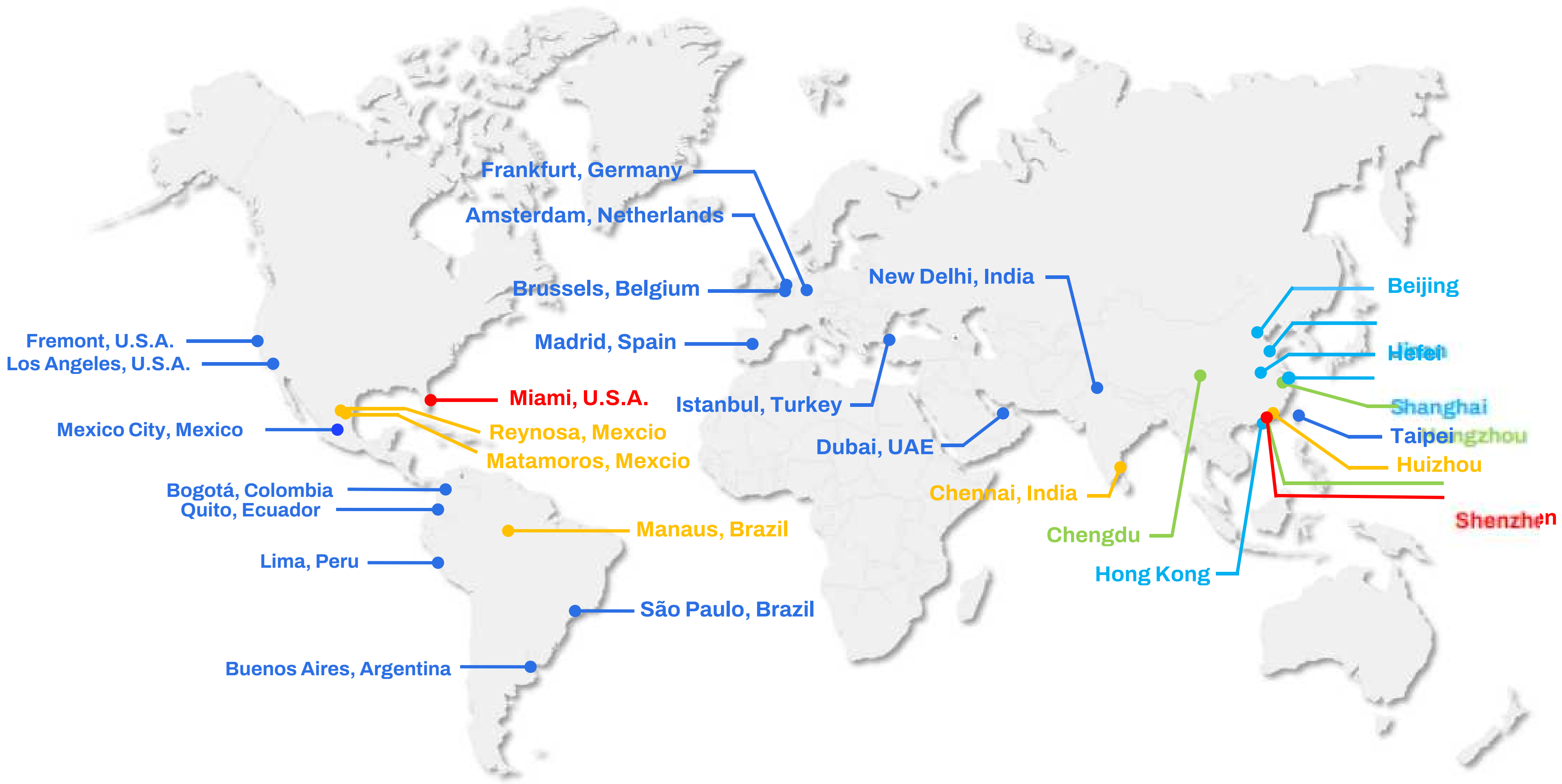
“Flip-chip”allows integrating the controller in the substrate

04

Sales and Marketing

Global Network, International Awards, Media Accolades, and Trade Shows

BIWIN Presence Reaches Across the Globe



● Headquarters

Global Headquarters: Shenzhen
America Headquarters: Miami

● R&D Centers

Shenzhen, Chengdu, Huizhou, Hangzhou

● Manufacturing Plants

Huizhou, Manaus, Chennai, Reynosa, Matamoros...

● Service Centers

Hong Kong, Beijing, Shanghai...

● Local Presence

Los Angeles, New Delhi, Frankfurt, Taipei, Mexico City...

International Awards and Honors

reddot winner 2022

reddot winner 2024

FRENCH DESIGN AWARD

iF DESIGN AWARD 2021

CES Innovation Awards 2025 Honoree

CES INNOVATION AWARDS 2018 HONOREE

FLASH MEMORY SUMMIT BEST OF SHOW

Most Innovative Technology

Certificate

BIWIN TECHNOLOGY LLC

The Leading Flash Storage Manufacturer Of 2022

The Leading Flash Storage Manufacturer

CERTIFICATE

TOP ACHIEVER AWARDS 2021

This is to certify that

BIWIN

is the Winner of

Top Achiever in Consumer Storage Awards

14th

dt AWARDS 2022

Congratulations For Winning

Editor's Pick

Most Reliable Flash Storage Manufacturer Brand

BIWIN

Most Reliable Flash Storage Manufacturer Brand Awards

* Each trademark belongs to its respective owner.

Media Accolades and What Press & Experts Say

tom's HARDWARE

"The Acer Predator GM7 is **the most efficient SSD we have ever tested**, and it's no slouch with regard to performance. It's good to great in most benchmarks, and performance in sustained workloads is also reasonably good. The great power efficiency helps keep the drive cool, and the single-sided design makes this a great choice for laptops and the PS5."

"**Best price-to-performance ratio** at MSRP we've ever seen." "The first DRAM-less SSD with enough throughput for the PS5."

"The GM7 SSD is one more successful product under the Predator brand. It pleasantly surprised me multiple times and gave me some fun testing a new and original SSD that has a chance to change something on the already dull storage market."

100+ Corporate & Product Awards Worldwide

* Each trademark belongs to its respective owner.

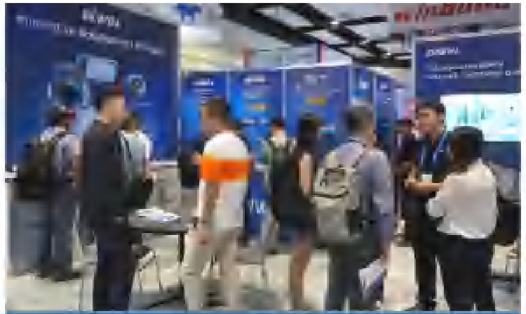
Worldwide Exhibitions

The industry gathers at trade shows to see the latest in product and technology.

Important buying decisions are often made on trade show floors. Certainly, lasting relationships form between the manufacturers and the buyers during these important events.

Only truly global companies are able to follow the international schedule of events that puts a storage manufacturer on the world map.

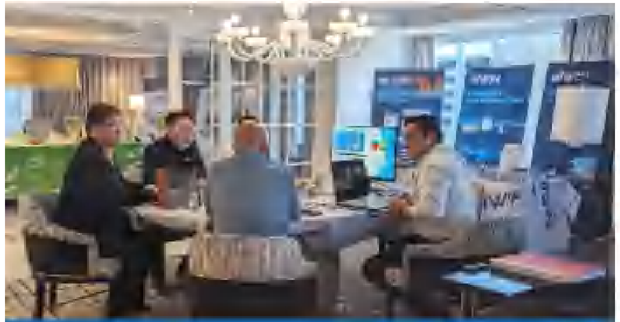
embedded world 2024



FMS2024

embedded world 2023

IT Week 2023



CES 2024

COMPUTEX 2024

GITEX 2024

Local Events, Promotions, Product Training

Germany

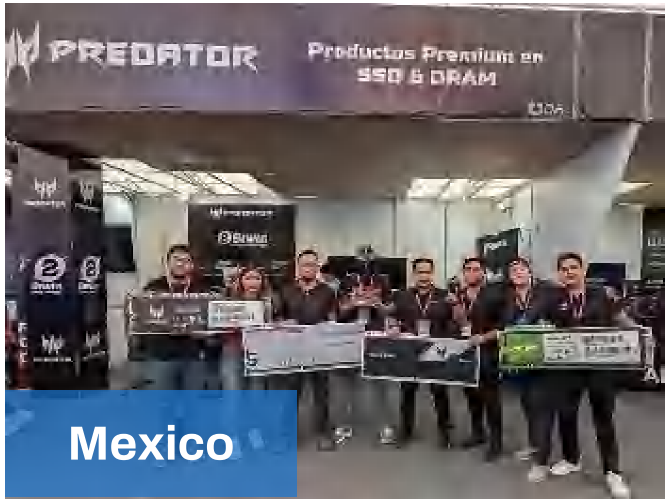
USA

India

Peru

Taipei

Spain



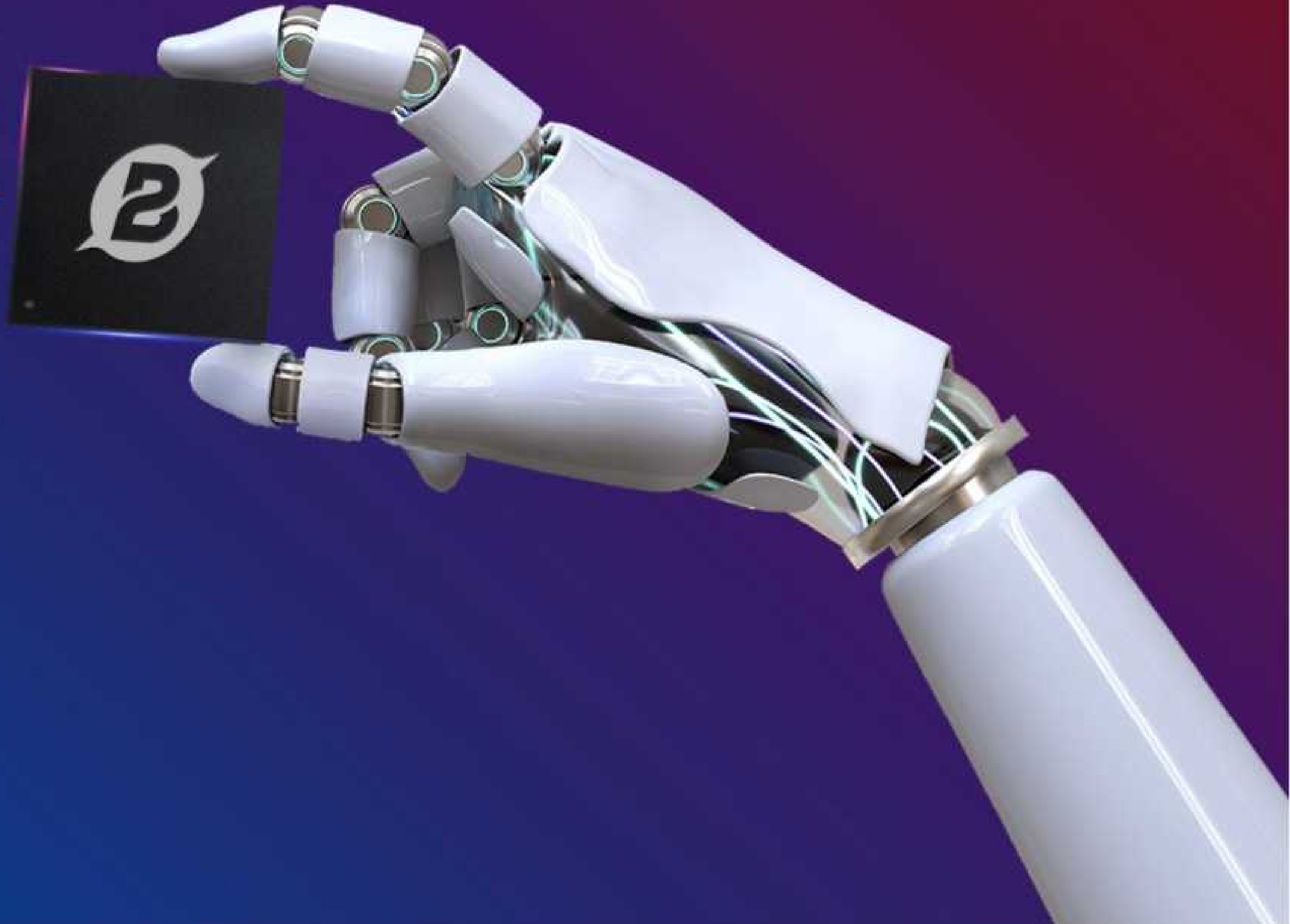
Mexico

Australia

05

BIWIN Advantages

Why BIWIN?

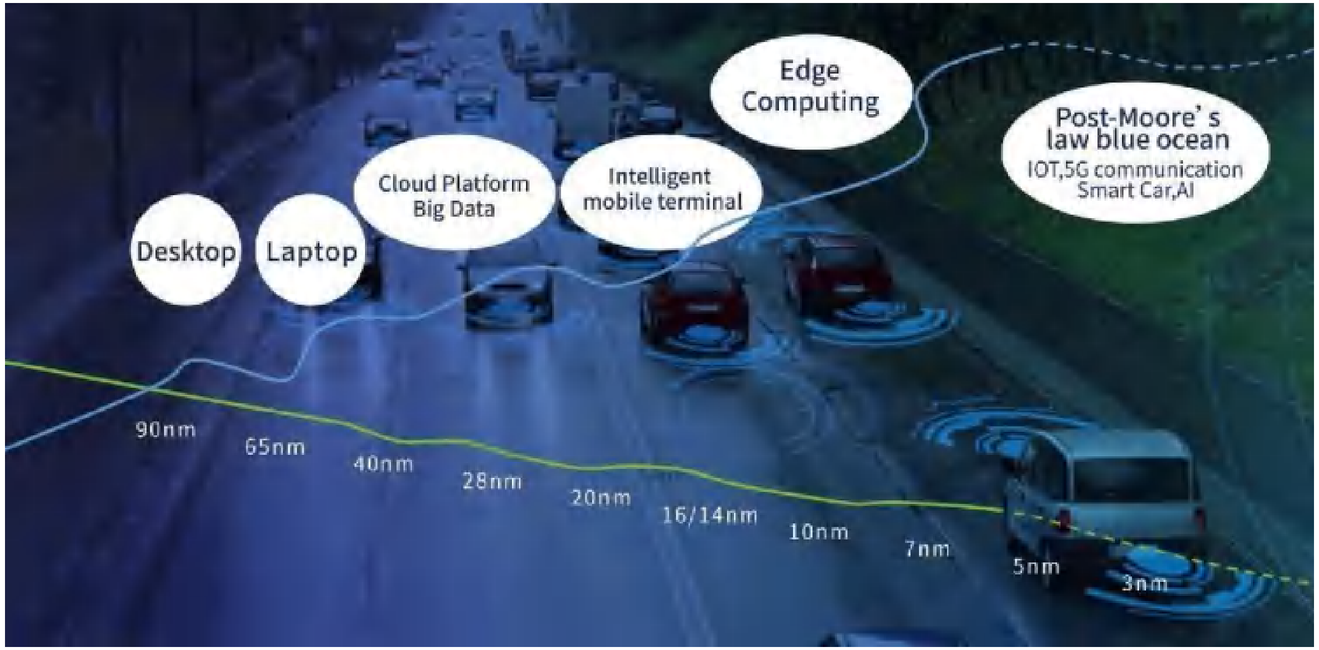


We’re a Specialist Manufacturer of Flash Storage & DRAM

First, we are manufacturing specialists of FLASH STORAGE and DRAM, products which are significant in **the era of Internet of Everything**.

There are not that many of us (compared to other industries), so we serve a WIDE range of embedded, industrial & consumer applications.

Our products ensure the speed and reliability of computing performance inside PCs, industrial equipment & connected devices.

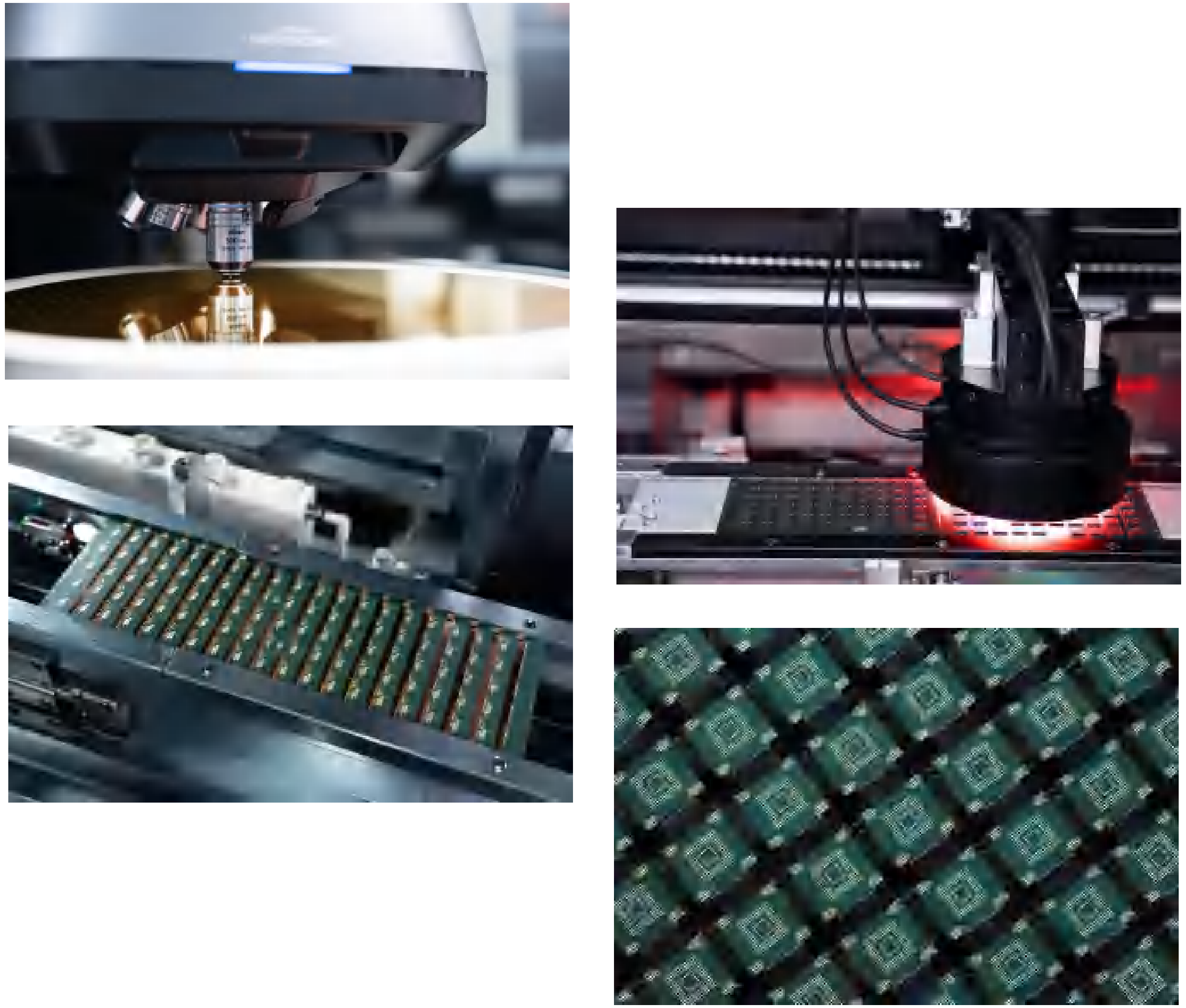


Our Expert Services for IC Packaging & Testing

Second, there aren’t many suppliers in flash storage and DRAM that also do **IC packaging and testing.**

That means that many other supplier must wait until the wafer producers (all large companies) do the packaging and stock their supply chain.

We offer a more flexible working relationship, more custom service, and improved time-to-market.



We’ve Learned Much from Working with Tech’s Top Companies

Third, because of our IC packaging and testing, many of the world’s top consumer brands (as well as exciting start-ups), do business with us **because of our decades of experience in IC packaging and testing** we can help customize their solutions.

Our work is based on years of experience meeting the needs of the world’s top brands.

We work with THREE of the FIVE BIG TECH companies below.

Our big clients want anonymity so we can only tell you we’re already supplying embedded storage to three out of the Big Five of the world’s largest tech companies (Alphabet (Google), Amazon, Apple, Meta (Facebook), and Microsoft.)

* Each trademark belongs to its respective owner.

We’re Also Working with the World’s Top PC Brands

Fourth, under official license, we make the consumer storage and DRAM several top tier PC brands. This is not OEM but a much rarer business model. We compete for **an official license to design, build, market and sell under these famous computer brands**.

Imagine that as a Top 5 Global PC company that your most important asset is your brand—and you’ll realize that **license-to-build is a well-scrutinized decision** in the first place--with constant communication between company teams to ensure any chosen supplier to live up to the brand expectations.

Our Newest Facility: We’ve Greatly Increased Capacity

Fifth, we opened Phase I of the new **BIWIN SCIENCE & TECHNOLOGY PARK**. It’s one of the latest modern factories in our industry and a 110,000 sqm facility.

With this new campus, our production capacity is increased by multiples, bringing us all the commercial advantages that bigger purchasing power can provide our customers.

We’re Now a Public Company

Sixth, After being chosen for inclusion in **the elite STAR MARKET Sci-Tech Innovation group**, BIWIN concluded its IPO listing on the Shanghai Stock Exchange.

Besides **a great vote of confidence in our future by the financial community**, this listing creates many financial advantages that will help us increase our visibility on the global stage.

Even Our Manufacturing Machinery is Award-Winning

We've designed and built some of our own manufacturing machinery. It worked so well, we've created a subsidiary to sell it industry-wide under its own brand Tytantest.

Our Tytantest TY-S101A won the **BEST OF SHOW Award for Most Innovative Memory Technology** at the 2023 Flash Memory Summit.

Why BIWIN? A Summary From This Presentation

Storage Algorithms & Firmware Development

BIWIN owns two R&D teams for firmware development. The core members have more-than-ten-year experience in firmware development, and have rich experience in mass production of self-developed firmware.

Full-range Product Testing Capability

BIWIN incessantly develops the memory chip testing algorithm and automation equipment. We lead the industries with our impressive test coverage and automation. Every product comes from us must undergo DVT and PVT.

Outstanding Customization, Fast Response

BIWIN boasts the extraordinary customized R&D capabilities and the fast response to customers' needs. We hereby can meet the all-round requirements of 5G, IoT, smart industry, smart city, and vehicle network.

Advanced Packaging & Testing

With the leading multi-chip and SiP packaging technology, BIWIN can process wafers as thin as 25 μm, support the mass production of 16-layer die stacking and achieve the smallest package in the industry.

Infinite Storage,
Unlimited Solutions

BIWIN STORAGE TECHNOLOGY CO., LTD.

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mkt.hq@biwintech.com